CLAIMS

- 1 1. A method of providing thermal connection between a
- 2 cooling device and a device to be cooled, the method comprising:
- 3 a. applying an adhesive to a thermal interface outside a
- 4 heat transfer area of the thermal interface;
- 5 b. attaching the thermal interface to the cooling device;
- 6 and
- 7 c. attaching the device to be cooled to the thermal
- 8 interface.
- 1 2. The method of claim 1 wherein said adhesive includes a
- 2 pressure sensitive adhesive (PSA).
- The method of claim 1 wherein said cooling device
- 2 includes a heat sink device.
- 1 4. The method of claim 1 wherein said cooling device
- 2 includes a thermal plate.
- 1 5. The method of claim 1 wherein said device to be cooled
- 2 includes an integrated circuit package.
- 1 6. The method of claim 1 wherein said adhesive is applied
- 2 at a periphery of said thermal interface.
- 1 7. The method of claim 1 wherein said thermal interface
- 2 includes a Chomerics T443 film.

- 1 8. An apparatus to provide thermal connection between a
- 2 cooling device and a device to be cooled, the apparatus
- 3 comprising:
- a thermal interface that includes a heat transfer area;
- 5 an adhesive applied to the thermal interface outside the
- 6 heat transfer area; and
- 7 a cooling device to which the thermal interface is
- 8 attached.
- 1 9. The apparatus of claim 8 wherein said adhesive
- 2 includes a pressure sensitive adhesive (PSA).
- 1 10. The apparatus of claim 8 wherein said cooling device
- 2 includes a heat sink.
- 1 11. The apparatus of claim 8 wherein said cooling device
- 2 includes a thermal plate.
- 1 12. The apparatus of claim 8 wherein said device to be
- 2 cooled includes an integrated circuit package.
- 1 13. The apparatus of claim 8 wherein said adhesive is
- 2 applied at a periphery of said cooling device.
- 1 14. The apparatus of claim 8 wherein said thermal
- 2 interface includes a Chomerics T443 film.
- 1 15. An apparatus comprising:
- 2 a thermal interface that includes a first surface with a
- 3 heat transfer area and a second surface;

- 4 an adhesive applied to the first surface outside the heat
- 5 transfer area;
- a cooling device attached to the thermal interface at said
- 7 first surface thereof; and
- 8 a device to be cooled attached at said second surface of
- 9 the thermal interface.
- 1 16. The apparatus of claim 15 wherein said adhesive
- 2 includes a pressure sensitive adhesive (PSA).
- 1 17. The apparatus of claim 15 wherein said cooling device
- 2 includes a heat sink.
- 1 18. The apparatus of claim 15 wherein said device to be
- 2 cooled includes an integrated circuit package.
- 19. The apparatus of claim 15 wherein said device to be
- 2 cooled includes a thermal plate.